

approach to manufacture low cost multilayer piezoelectrics. The method of the invention is performed at low firing temperature and without the oxidation of base metal or reduction of ceramic components. A variety of ceramic materials may be used and copper is the preferred base metal in the multi-layer piezoelectric devices of the invention. This copper has additional protection against oxidation with a small inorganic coating on the surface. With such protection, the binder and other organics can also be efficiently removed and produce superior performance in the piezoelectric structured devices.

**In the Claims:**

The claims have been amended as follows:

1. (Amended) A process for preparing a multilayer piezoelectric device with alternating piezoelectric ceramic layers and base metal layers as electrodes comprising the steps of:
  - (a) applying onto a first layer, which includes a piezoelectric ceramic material and a first combination of organic materials, a second layer, which includes a base metal powder having particles, which are coated with material capable of protecting said base metal against oxidation, and a second combination of organic materials, to produce a first structure;
  - (b) applying onto said first structure a second structure, which is identical to said first structure to produce a multilayer structure;